ABSTRACT

A method and apparatus for peeling protective adhesive tape 3 from work having the protective adhesive tape 3 applied to a surface of a semiconductor wafer W supported in a ring-shaped frame F by means of a supporting adhesive tape 1. Thin plates 4 with non-adhesive upper surfaces are applied to the supporting adhesive tape 1 adjacent a peel starting end 3a and a peel finishing end 3b of protective adhesive tape 3, respectively, to form regions for avoiding contact between a peeling tape 5 wound around an applying roller 8 and the like and the supporting adhesive tape 1. Subsequently, the peeling tape 5 is applied to the protective adhesive tape 3 at the peel starting end 3a with the applying roller 8, and a group of rollers 6-8 is moved horizontally on the work A to peel the peeling tape 5 and protective adhesive tape 3 together from the surface of semiconductor wafer W.